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(12) **United States Design Patent** (10) **Patent No.:** **US D548,200 S**  
**Hayashi** (45) **Date of Patent:** **\*\* Aug. 7, 2007**

(54) **ATTRACTING DISC FOR AN ELECTROSTATIC CHUCK FOR SEMICONDUCTOR PRODUCTION**

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(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/245,048**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
156/345.53; 279/128; 361/234

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for an attracting disc for an electrostatic chuck for semiconductor production, as shown and described.

**DESCRIPTION**

FIG. 1 is a front elevational view of an attracting disc for an electrostatic chuck for semiconductor production, showing my new design;

FIG. 2 is a rear elevational view thereof;

FIG. 3 is a left side elevational view thereof;

FIG. 4 is a right side elevational view thereof;

FIG. 5 is a top plan view thereof; and,

FIG. 6 is a bottom plan view thereof.

The broken line showing in the figures is for illustrative purposes only and forms no part of the claimed design.

**1 Claim, 3 Drawing Sheets**

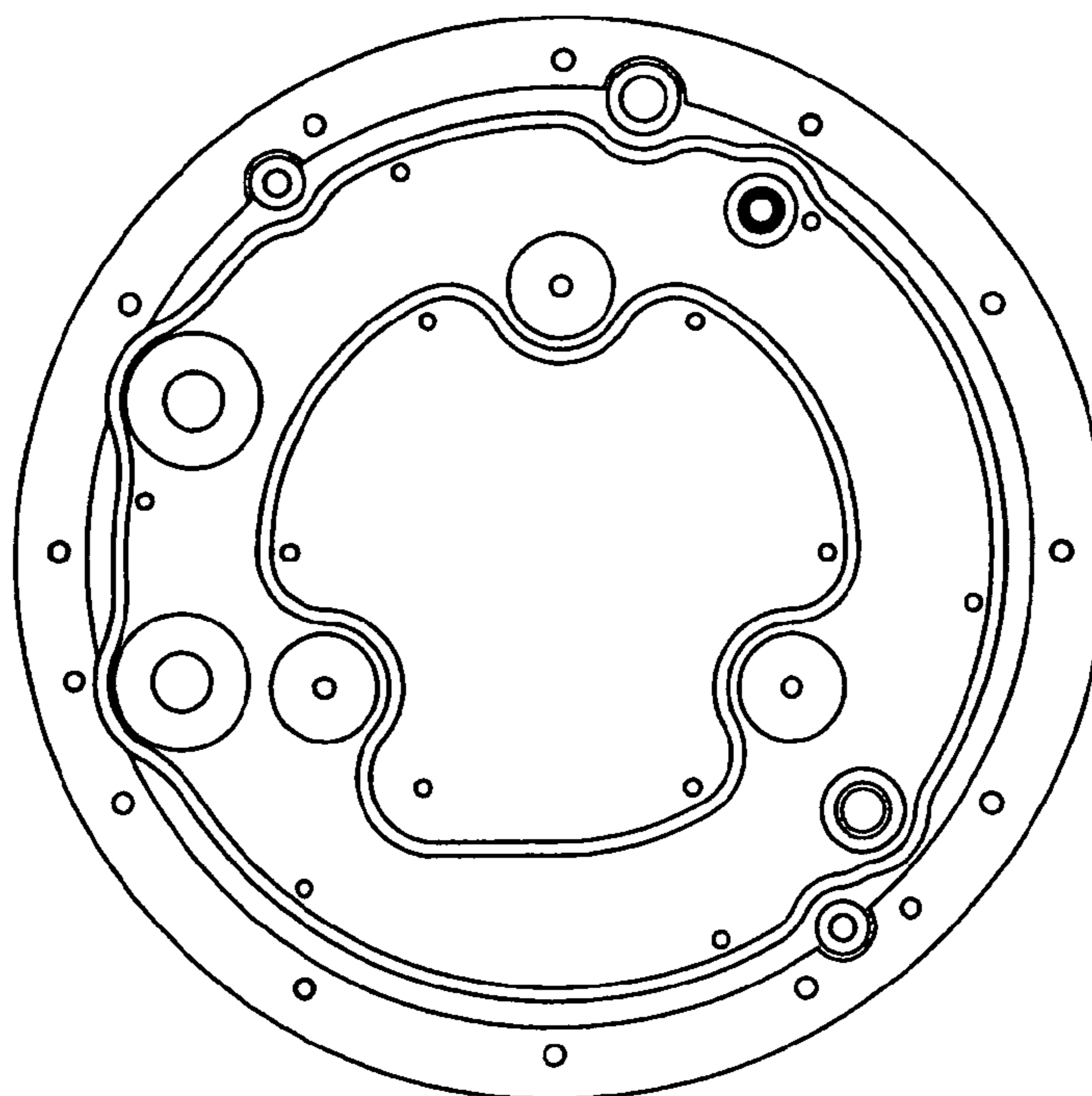


FIGURE 1

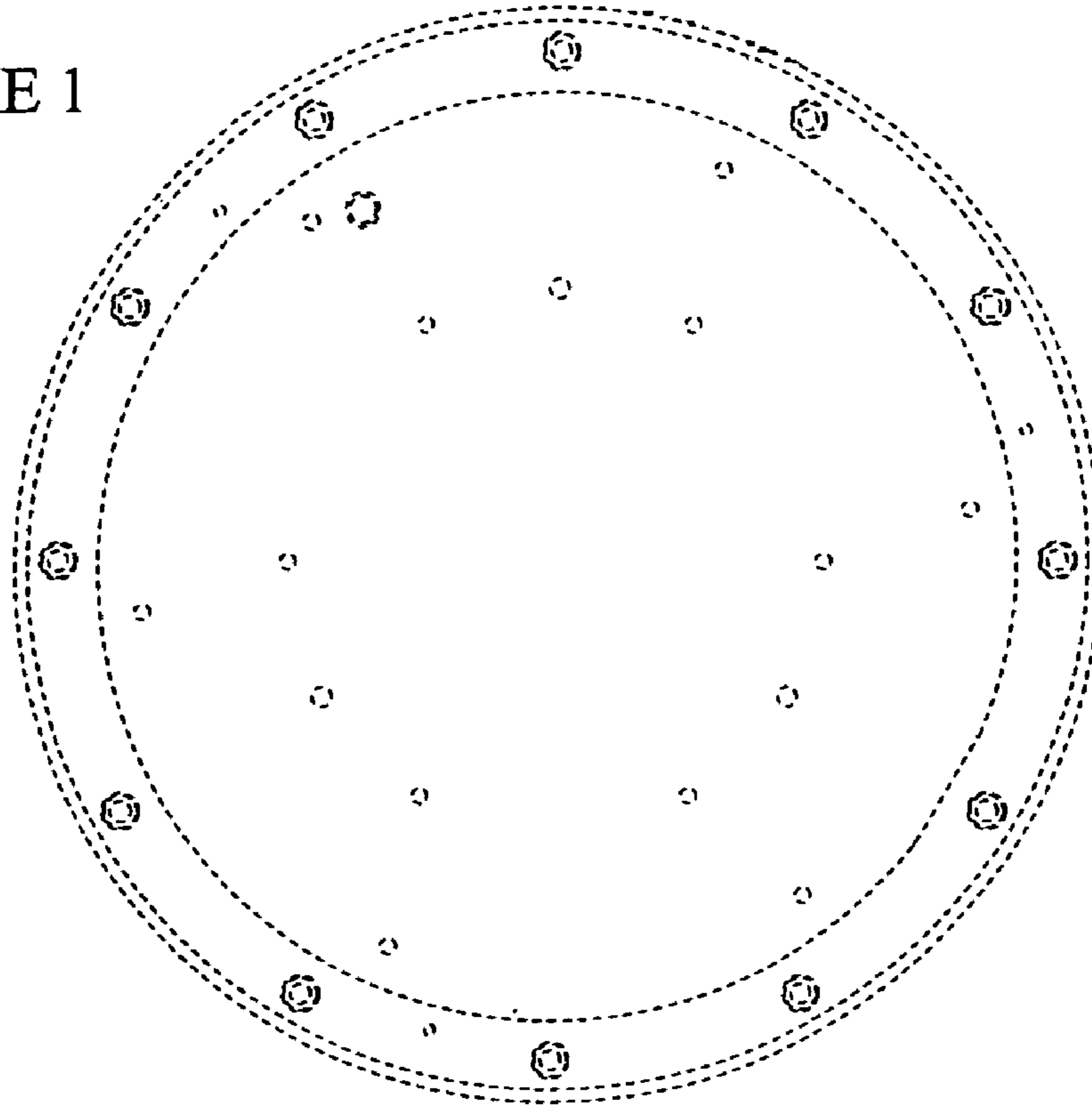


FIGURE 2

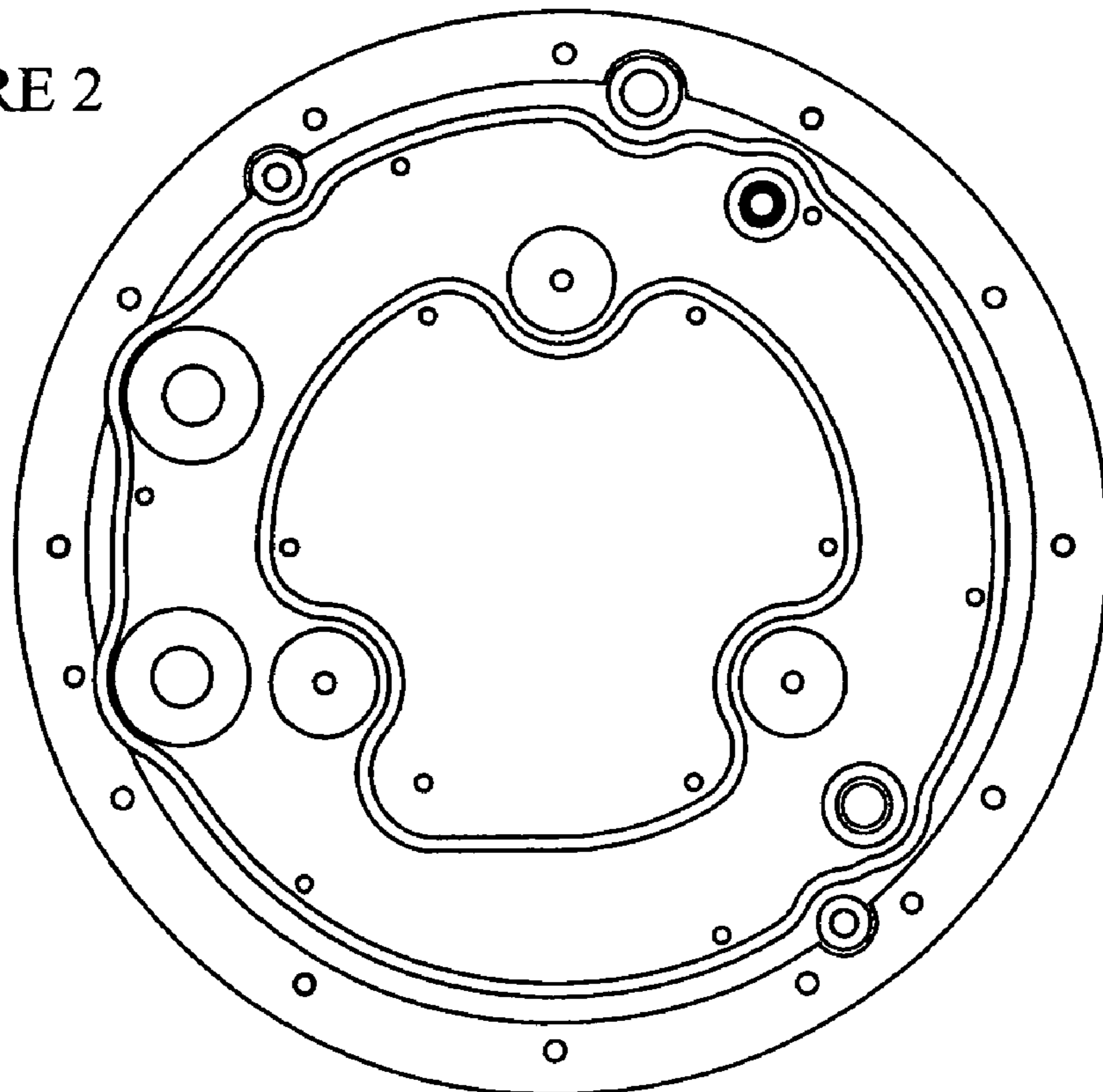


FIGURE 3



FIGURE 4

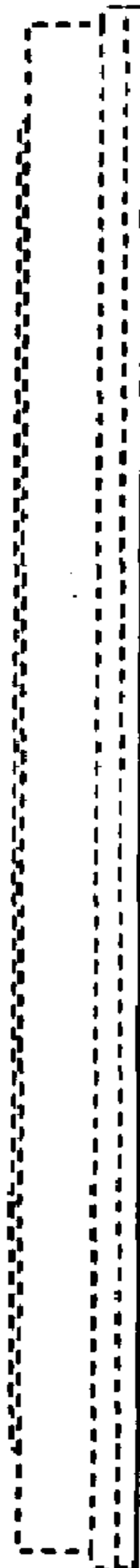


FIGURE 5

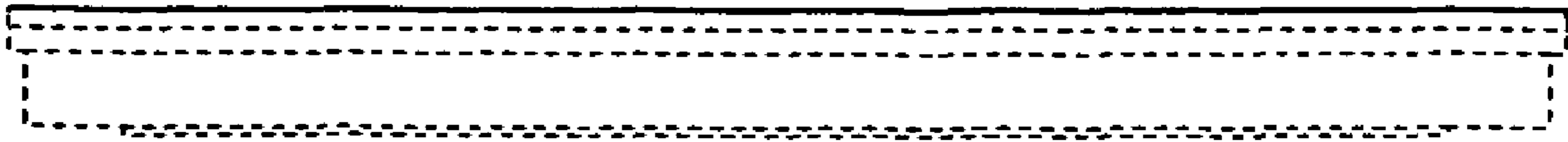


FIGURE 6

